

4.5mm Square Compact (Snap-in Type)



Compact snap-in type improves high density mounting.



Typical Specifications

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Items	Specifications	
Rating (max.)	50mA 12V DC	
Rating (min.)	10μA 1V DC	
Initial contact resistance	100mΩ max.	
Travel (mm)	0.25	

Detector

Push

Slide

Rotary

Encoders

Power

Dual-in-line Package Type

TACT Switch™

Sharp Feeling Soft Feeling Snap-in

Type
Surface
Mount Type
Radial
Type

Product Line

Product No.	Operating force	Operating direction	Operating life	Stem color	Minimum order unit (pcs.)		
Product No.	Operating force	Operating direction	(5mA 5V DC)		Japan	Export	
SKHRAAA010	0.98N		50,000cycles	Black			
SKHRABA010	1.57N	Toppush	30,000cycles	Dark gray	1,000	1,000	
SKHRAHA010	2.55N		50,000cycles	Red			

Packing Specifications

Bulk

Number of pa	Export package	
1 case / Japan	1 case / export packing	measurements (mm)
20,000	60,000	309 × 476 × 347

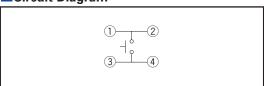
DimensionsUnit:mm

Dimensions	Unit:mm
Style	PC board mounting hole dimensions (Viewed from switch mounting face)
1	4-ø1 holes/ 5

Note

Please use 1.6mm thick PC boards.

Circuit Diagram



TACT Switch™

List of Varieties

Detector Push Slide **Rotary Encoders** Power Dual-in-line Package Type TACT Switch™

Sharp Feeling Soft **Feeling** Snap-in Type

Surface **Mount Type** Radial

Type

Type		Sharp Feeling Type									
							p–in	<u> </u>			
	Series	SKHR	SKHL	SKHH	SKHW	SKQJ	SKQB	SKQE	SKHC	SKHL	SKHH
	Photo										
	Features	_	_	_	_	_	_	Long Life	_	_	_
v	Vater-proof	_	_	_	0	_	•	_	_	_	_
ı	Dust-proof	_	_	_	•	•	•	•	_	_	_
Operatii	Top push	•	•	•	•	•	•	•	•	_	_
direction	Side push	_	_	_	_	_	_	_	_	•	•
Dimensio	W	□ 4.5	6		6	□ 6.6	□ 10		12	7.3	7.5
(mm)	D		3.5							7.22	7.85
	H ~1N	3.8	↑	4.3		5 ↑	5		4.3		7.4
Operation	on 1N~2N				1		1	1			
force coverage		*	—		*		*	—		·····	*
	4N~5N			—							
1	Travel (mm)		0.25		0.3	0.25		0.3		0.2	25
Gro	ound terminal	_	_	•	_	_	_	_	_	•	•
Operat	ting temperature range	- 30°C to + 85°C - 40°C to + 90°C			- 30°C to + 85°C	$-40^{\circ}\text{C to} + 90^{\circ}\text{C}$ $\begin{vmatrix} -40^{\circ}\text{C to} \\ +85^{\circ}\text{C} \end{vmatrix}$ $-40^{\circ}\text{C to} + 90^{\circ}\text{C}$) + 90°C		
Aut	tomotive use	- • • -			_	_	_	_	_		
	Life Cycle	* 2	* 2	*3	*3	* 2	* 2	* 2	* 2	**3	*3
	ating (max.) esistive load)					50mA 1	2V DC				
	ating (min.) esistive load)					10 μ A	1V DC				
Electrical	Insulation resistance	100M Ω min. 100V DC for 1min.									
performance	Voltage proof	250V AC for 1min.									
	Vibration	10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2hours respectively									
Durability	Lifetime	Shall be in accordance with individual specifications.									
	Cold	– 40 \pm 2°C for 96h			- 30 ± 2°C for 96h	$-430\pm2^{\circ}\mathrm{C}$ for 96h					
Environmental performance	Dry heat	90 ± 2°C for 96h			- 80 ± 2°C for 96h	90 ± 2°C for 96h					
	Damp heat	$60\pm2^{\circ}\mathrm{C}$, 90 to 95%RH for 96h			60 ± 2°C , 90 to 95%RH for 1000h		60 ± 2°C,	90 to 95%l	RH for 96h		
	Page	229	230	232	236	237	239	241	243	230	232
						Width The					

W: Width. The most outer dimension excluding terminal portion.

D: Depth. The most outer dimension excluding terminal portion.

H: Height. The minimum dimension if there are variances.

■ TACT Switch[™] Soldering Conditions · · · 288 ■ TACT SwitchTM Cautions · · · ·

- The automotive operating temperature range to be individually discussed upon request.
 indicates applicability to all products in the series, while indicates applicability to some products in the series.

TACT Switch™ Soldering Conditions

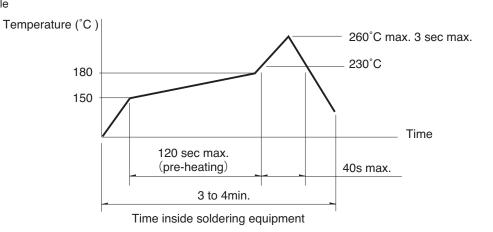
Condition for Reflow

Available for Surface Mount Type.

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at solder joints (copper foil surface) .

A heat resistive tape should be used to fix thermocouple.

3. Temperature profile



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Sharp Feeling Soft

Feeling Snap-in Type Surface Mount Type

Radial Type

Notes

- 1. The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip Available for Snap-in Type and Radial Type

Items	Condition		
Flux built-up	Mounting surface should not be exposed to fluk		
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.		
Preheating time	60s max.		
Soldering temperature	260°C max.		
Duration of immersion	5s max.		
Number of soldering	2times max.		

SKHH、SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to fluk
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKOJ. SKOK. SKEG Series

SNQJ, SNQN, SNEG Series			
Items	Condition		
Flux built-up	Mounting surface should not be exposed to fluk		
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.		
Preheating time	45s max.		
Soldering temperature	255℃ max.		
Duration of immersion	5s max.		
Number of soldering	2times max.		

Manual Soldering (Except SKRT Series)

Items	Condition		
Soldering temperature	350°C max.		
Duration of soldering	3s max.		
Capacity of soldering iron	60W max.		

SKHH、SKHW、SKRG、SKPD Series

Items	Condition		
Soldering temperature	360°C max.		
Duration of soldering	3s max.		
Capacity of soldering iron	60W max.		

SKQJ、SKQK、SKEG Series

Items	Condition		
Soldering temperature	350°C max.		
Duration of soldering	3s max.		
Capacity of soldering iron	20W max.		

Notes

- 1. Consult with us for availability of TACT Switch[™] washing.
- 2. Prevent flux penetration from the top side of the TACT Switch $^{\text{TM}}$.
- 3. Switch terminals and a PC board should not be coated with flux prior to soldering.
- The second soldering should be done after the switch is stable with normal temperature.
- 5. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)